



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Keith E. FOGEL et al. CONFIRM. NO.: 6557
SERIAL NO.: 10/815,103 ART UNIT: 2826
FILED: 03/31/2004 EXAMINER: L. ANDUJAR
TITLE: INTERCONNECTIONS FOR FLIP-CHIP USING LEAD-FREE
SOLDERS AND HAVING REACTION BARRIER LAYERS

ATTORNEY DOCKET NO.: YOR920030190US1

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL OF FORMAL DRAWINGS

Sir:

Enclosed are three sheets of formal drawings to replace the informal drawings currently on file.

Respectfully submitted,

David Aker
David Aker, Reg. No. 29,277
23 Southern Road
Hartsdale, NY 10530

4/30/2007
Date

Tel. & Fax 914 674-1094

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 30, 2007
Date

David Aker
Name of Person Making Deposit